

## PMP10748 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
PCB	1		PMP10748	Any	Printed Circuit Board	
C1, C21	2	100pF	08055A101JAT2A	AVX	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
C3in, C4, C4in, C5	4	4.7uF	GRM32ER71H475KA88L	MuRata	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1210	1210
C8, C33	2	0.1uF	C2012X7R2A104K	TDK	Ceramic, X7R, 100V, 10%	0805
C11		0.22uF	C0805C224K5RACTU	Kemet	CAP, CERM, 0.22 µF, 50 V, +/- 10%, X7R, 0805	0805
C55	1	220uF	EEE-FC1H221P	Panasonic	CAP, AL, 220 µF, 50 V, +/- 20%, 0.3 ohm, SMD	SMT Radial G
C56	1	1000uF	EEV-FK1H102M	Panasonic	CAP, AL, 1000 μF, 50 V, +/- 20%, 0.073 ohm, SMD	SMT Radial J16
DRV1, DRV2, DRV3, H1, H2, Output, Output, VIN1, VIN2	9	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
EN	1	Double	1503-2	Keystone Electronics	Terminal, Turret, TH, Double	
FET1_B, FET2_B, FET3_A	3	40V	SQJ422EP-T1-GE3	Vishay-Siliconix	MOSFET, N-CH, 40 V, 75 A, PowerPAK_SO-8L	PowerPAK_SO-8L
GND1, GND2, GNDout	3	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
GND, J4	2		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J3, VBAT_1, VBAT_2	3		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
L1, L2	2	White	5012	Keystone	Test Point, Multipurpose, White, TH	White Multipurpose Testpoint
R2	1	240k	CRCW0805240KJNEA	Vishay-Dale	RES, 240 k, 5%, 0.125 W, 0805	0805
R3	1	14.0k	CRCW080514K0FKEA	Vishay-Dale	RES, 14.0 k, 1%, 0.125 W, 0805	0805
R4	1	4.99k	CRCW12064K99FKEA	Vishay-Dale	RES, 4.99 k, 1%, 0.25 W, 1206	1206
R5	1	0	CRCW06030000Z0EA	Vishay-Dale	5%, 0.1W	0603
R6	1	100k	CRCW0603100kFKEA	Vishay-Dale	1%, 0.1W	0603
Ru	1	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
STATUS	1	SMT	5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_ Miniature
TP3, TP4	2	Orange	5013	Keystone	Test Point, Multipurpose, Orange, TH	Orange Multipurpose Testpoint
U1, U2	2		LM74610QDGKRQ1	Texas Instruments	Smart Diode Controller, DGK0008A	DGK0008A
U3	1		LM5060Q1MM/NOPB	Texas Instruments	High-Side Protection Controller with Low Quiescent Current, 10-pin MSOP, Pb-Free	MUB10A
VCAP_1, VCAP_2	2	2.2uF	C2012X5R1H225K125AB	TDK	CAP, CERM, 2.2 μF, 50 V, +/- 10%, X5R, 0805	0805
FET1_A, FET2_A	0	40V	CSD18501Q5A	Texas Instruments	MOSFET, N-CH, 40 V, 22 A, SON 5x6mm	SON 5x6mm
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
Q1	0	100V	SUM40N10-30	Vishay-Siliconix	40A, 35nC, rDS(on) @ 4.5V =	DDPAK
Ro	0	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805

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